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MEG 01-015

AMENDMENTS

IN THE CLAIMS

I-241. (canceled)

242. (currently amended) A chip packaging method comprising:
joining a die and a substrate;
after said joining said die and said substrate, depositing a passive device over said
substrate, wherein said passive device has a portion not over said die; and
separating said substrate.

243. (currently amended) A chip packaging method comprising:
joining a die and a substrate, said die having a top surface at a horizontal level;
after said joining said die and said substrate, depositing a passive device over said
substrate horizontal level, wherein said passive device has a first end connected down to said die
and a second end connected to a topmost pad of said chip package; and
separating said substrate.

244. (currently amended) A chip packaging method comprising:
providing a die having a top surface at a horizontal level;
depositing a passive device over said horizontal level, wherein said passive device has a
portion not over said die; and

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depositing a trace over said horizontal level, wherein said trace has a portion not over said
die, and extends to a place under which said die does not exist.